

MATERIAL LITIGATION AMKOR'S COMPLAINT

MALAYSIAN PACIFIC INDUSTRIES BERHAD

Type	Announcement
Subject	MATERIAL LITIGATION
Description	AMKOR'S COMPLAINT

We refer to Malaysian Pacific Industries Berhad (“MPI”)’s announcement dated 18 February 2014 in respect of the on-going patent litigation between Carsem (M) Sdn Bhd, Carsem Semiconductor Sdn Bhd (now known as Recams Sdn Bhd) and Carsem Inc. (collectively referred to as “Carsem”) and Amkor Technology, Inc. (“Amkor”).

MPI writes to inform that the International Trade Commission (“ITC”) has, on 4 April 2014, issued a limited exclusion order (“Order”) on importation of the related package into the United States (“US”) [“ITC Decision”]. The ITC Decision finds that some but not all of Carsem’s Micro Leadframe Package (“MLP”) designs infringe the Amkor’s US patent.

The Order is subject to a 60-day period of “Presidential review” during which Carsem can freely import the affected package by posting a bond. In the meantime, Carsem is considering all options to remedy the ITC Decision.

The Order is limited in scope and does not apply to any of Carsem’s customers’ downstream products containing the affected MLP packages, nor does it affect Carsem’s other package products.

In contrast to the ITC Decision, the US Patent and Trademark Office has recently issued a decision finding that the patent claims the ITC found infringed are invalid. Carsem expects Amkor to appeal against that decision. In the event the appeal is unsuccessful, Carsem will have the ITC’s Order withdrawn.

The ITC Decision is not expected to have any material impact on the earnings per share of MPI Group for the current financial year ending 30 June 2014.

This announcement is dated 8 April 2014.

Announcement Info

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